

*Copy*  
**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 3723**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Makoto KOBAYASHI et al.

Group Art Unit: 3723

Application No.: 09/830,434

Examiner: H. Shakeri

Filed: April 26, 2001

Docket No.: 109352

For: POLISHING PAD AND POLISHING METHOD FOR SEMI-CONDUCTOR WAFER

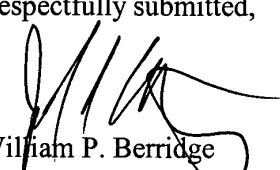
**TRANSMITTAL OF COURTESY COPY**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Attached is a courtesy copy of an Amendment After Final Rejection that was filed on  
September 17, 2003 in the above-captioned patent application.

Respectfully submitted,

  
William P. Berridge  
Registration No. 30,024

Christopher W. Brown  
Registration No. 38,025

Joel S. Armstrong  
Registration No. 36,430

**RECEIVED**  
SEP 23 2003

TECHNOLOGY CENTER R3700

WPB/CWB/JSA:amw

Date: September 22, 2003

**OLIFF & BERRIDGE, PLC**  
P.O. Box 19928  
Alexandria, Virginia 22320  
Telephone: (703) 836-6400

**DEPOSIT ACCOUNT USE  
AUTHORIZATION**

Please grant any extension  
necessary for entry;  
Charge any fee due to our  
Deposit Account No. 15-0461

COPY

**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 3723**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Makoto KOBAYASHI et al.

Group Art Unit: 3723

Application No.: 09/830,434

Examiner: H. Shakeri

Filed: April 26, 2001

Docket No.: 109352

For: POLISHING PAD AND POLISHING METHOD FOR SEMI-CONDUCTOR WAFER

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the June 17, 2003 Office Action, please consider the following:

**Amendments to the Claims** as reflected in the listing of claims; and

**Remarks.**